

仕样书编号 NO.: QW-QA-332 REV1.0

CUSTOMER:

日期 DATE: 2009-03-27

# 纳入仕样书 SPECIFICATION

产 品 名 称 PRODUCT NAME: 叠层片式天线

Multilayer Chip Antenna

贵 司 料 号 YOUR PART NO.:

敝 司 料 号 OUR PART NO.: MGMA3216H2450-A02

接受 RECEPTION

THE SPECIFICATION HAS BEEN ACCEPTED.

该纳入仕样书已被我司接受

日期:  
DATE:

公司:  
COMPANY:

批准  
CFMD

审核  
CHKD

接收  
RCVD

本纳入仕样书共 13 页

MANUFACTURING NAME

深圳市麦捷微电子科技股份有限公司

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CFMD. 批准	CHKD. 审核	DSGD. 担当
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## 目录 CATALOG

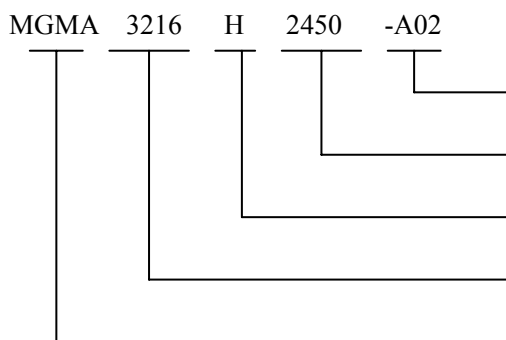
1 适用范围 Scope.....	3
2 品名构成 Product Identification.....	3
3 形状、尺寸 Appearance and Dimensions.....	3
4 测试电路及测试条件 Testing Conditions.....	3
5 电气性能 Electrical Characteristics.....	4
6 特性曲线 Characteristic curve.....	5
7 信赖性试验 Reliable Performance.....	6
8 焊接条件 Recommended Soldering Conditions.....	8
9 包装 Packaging.....	9
10 装箱清单及标志 Packing documents and marking.....	10
11 保管 Storage.....	12
APPENDIX A	
纳入仕様书改定履历 Modify History of Specification .....	13

## 1 适用范围 Scope

"麦捷"微波叠层片式介质天线 MGMA 系列产品, 设计用于 WLAN、HomeRF、Bluetooth、Module 等, 小体积 SMD 片式设计。

"Microgate" Microwave Multilayer Chip Antenna series are designed to be used in WLAN、HomeRF、Bluetooth、Module、etc, small size SMD chip design.

## 2 品名构成 Product Identification



标准规格, 编号: A02/Normaling Type: A02

中心频率/ Center Frequency: 2450MHz

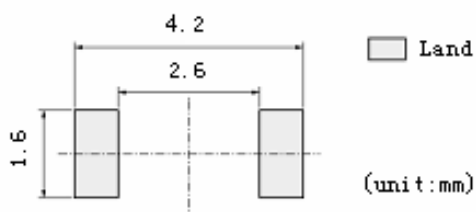
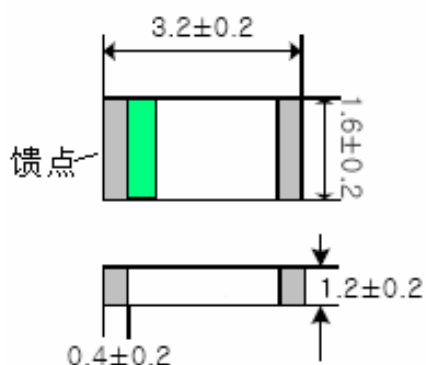
结构: 过孔设计

产品尺寸:  $3.2 \times 1.6 \times 1.2\text{mm}$

多层结构天线/Multi-layer Chip Antenna

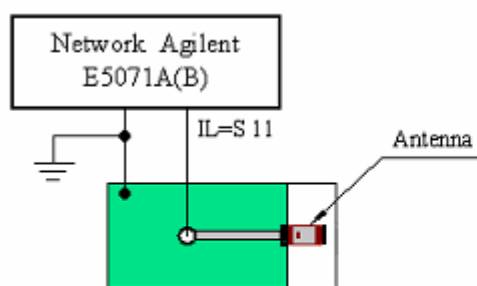
## 3 形状、尺寸 Appearance and Dimensions

Unit: mm

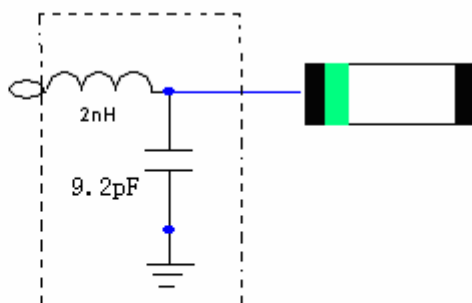


All the technical data and information specified herein are subject to variation without prior notice

## 4 测试电路及测试条件 Test Circuit and Testing Conditions



无匹配电路测试-3.5GHz中心频率  
No Matching Circuit Testing



LC 匹配电路  
LC Matching Circuit Testing

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除非另有规定，否则在以下条件下测试 <Unless otherwise specified>

温度 Temperature : Ordinary Temperature (5 to 35℃)  
湿度 Humidity : Ordinary Humidity (25 to 85% RH)

大气压强 Atmospheric Pressure : 86 to 106 kPa

当对测量结果有疑问时<In case of doubt>

温度 Temperature : 20±2℃  
湿度 Humidity : 55 to 75% RH  
大气压强 Atmospheric Pressure : 86 to 106 kPa

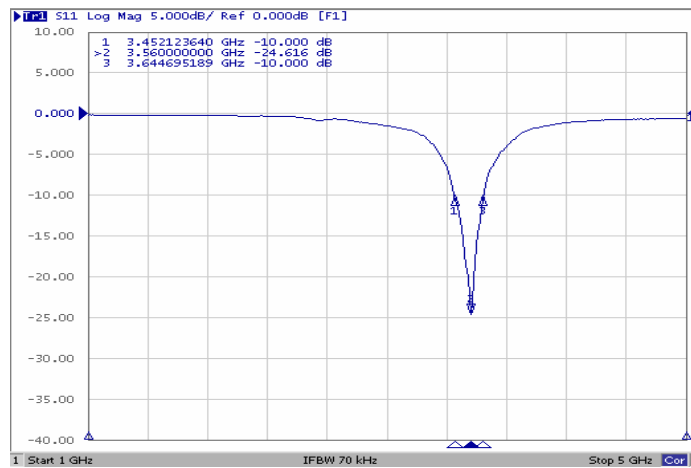
5 电气性能 Electrical Characteristics

操作温度范围 Operating Temperature Range : -40 to +85℃

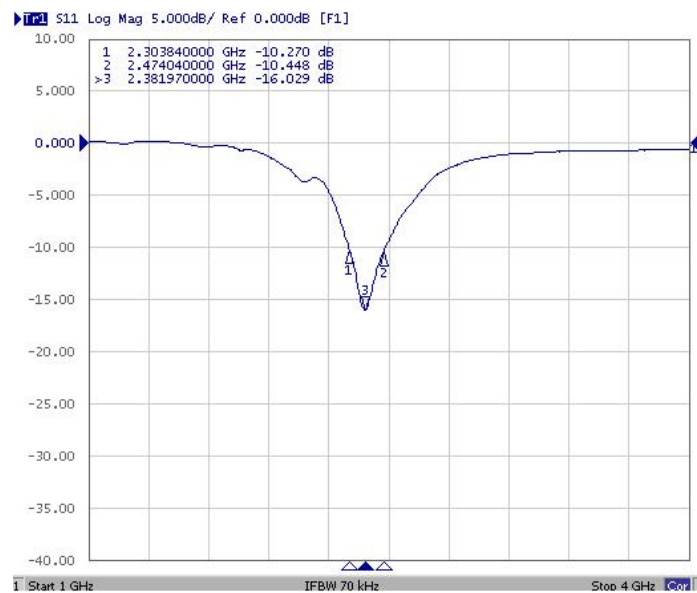
保存温度范围 Storage Temperature Range : -40 to +85℃

No.	Item (项目)	Specifications (特性)
1	Central Frequency 中心频率 (No matching)	3500MHz
	(带匹配电路测试)After Matching	2450 MHz
2	Band Width 通带宽度(No matching)	200 MHz ( 3400~3600MHz )
	(带匹配电路测试)After Matching	100 MHz ( 2400~2500MHz )
3	Gain 增益	0~2 dBi
4	V. S. W. R (in BW) 驻波比	≤2.0
5	Polarization 极化方式	Linear 线性
6	Azimuth Beam width 方位角	Omni-directional 全向
7	Impedance 阻抗	50 Ω

## 6 特性曲线 Characteristic curve

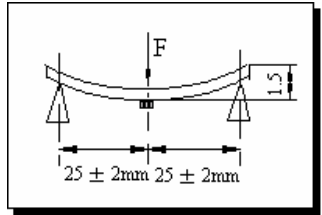


1) Before Matching



2) After Matching

## 7 信赖性试验 Reliable Performance

NO.	Item	Specifications	Test Methods	
7-1	Solder-Ability 可焊性	More than 90% of termination should be covered with new solder. 端电极焊锡覆盖率为90%以上。	焊锡 Solder: Sn: Pb=	100:0
			焊锡温度 Temperature:	255℃+5℃/-0℃
			助焊剂 Flux: 松香 rosin	
			浸渍时间 Duration:	5±0.5s
7-2	Leaching Resistance 耐焊性	More than 75% of termination Should be covered with new solder. 端电极焊锡覆盖率为75%以上	焊锡 Solder: Sn: Pb=	100:0
			焊锡温度 Temperature:	270℃+2℃/-0℃
			助焊剂 Flux: 松香 rosin	
			浸渍时间 Duration:	10±0.5s
7-3	Terminal Strength 端头强度	The terminal and body should be no damage 端头和瓷体不应见损伤	The device should not be broken after tensile force of 1.0kg is slowly applied to pull a lead pin of the fixed device in the lead axis direction for 10±1 seconds. 在产品电极端子上或表面上应能承受 1kg 垂直拉力 10±1 秒	
7-4	Bending Strength 弯曲试验	No mechanical damage should be noticed 不应见机械损伤	<p>Weld the product to the center part of the PCB with the thickness 1.6±0.2mm as the illustration shows, and keep exerting force arrow-ward on it at speed of: 1mm/S, and hold for 5±1S at the position of 1.5mm bending distance, so far, any peeling off of the product metal coating should not be detected.</p> <p>将产品按图焊在 1.6±0.2mm 的 PCB 板中间, 由箭头方向施力 1mm/S, 弯曲距离 1.5mm, 保持 5±1S, 产品金属层无脱落。</p> 	

NO.	Item	Specifications	Test Methods
7-5	Drop 跌落	Post Environmental Tolerance (环境试验后允许附加误差)	Drop 10 times on a concrete floor from a height of 1m. 从距混凝土地面 1m 高度自由落下, 重复 3 次。
7-6	Vibration 振动		频率 Frequency: 10 to 55Hz 振幅 Amplitude: 1.5mm 方向及时间 Direction and time: X, Y and Z directions for 2 hours each.
7-7	Humidity resistance 耐潮湿		a. 试验条件 Test condition 温度 Temp.: $60\pm 2^{\circ}\text{C}$ 湿度 Humidity: 90%~95% 试验时间 Test time: $96\pm 2\text{ h}$ b. 测量条件 Measurement method: 试验后常温常湿环境中放置 ( $24\pm 2$ ) 小时后测量。 The component should be stabilized at normal condition for ( $24\pm 2$ ) hours before test.
7-8	High temperature resistance 耐高温		a. 试验条件 Test condition 温度 Temp.: $+85\pm 2^{\circ}\text{C}$ 试验时间 Test time: $96\pm 2\text{ h}$ b. 测量条件 Measurement method: 试验后常温常湿环境中放置 ( $24\pm 2$ ) 小时后测量。 The component should be stabilized at normal condition for ( $24\pm 2$ ) hours before test.
7-9	Low temperature resistance 耐低温		a. 试验条件 Test condition 温度 Temp.: $-40\pm 2^{\circ}\text{C}$ 试验时间 Test time: $96\pm 2\text{ h}$ b. 测量条件 Measurement method: 试验后常温常湿环境中放置 ( $24\pm 2$ ) 小时后测量。 The component should be stabilized at normal condition for ( $24\pm 2$ ) hours before test.
7-10	Thermal shock (Temperature cycle) 热冲击 (温度循环)	1 Center Frequency 中心频率: $\pm 25\text{ MHz}$ ; 2 Band Width 通带宽度: $\pm 20\text{ MHz}$ ; 3 Gain 增益: $\pm 0.2\text{ dBi}$ 4 V.S.W.R (in BW) 驻波比: $\pm 0.5\text{ dB}$ ;	a. 试验条件 Test condition 1) 温度 Temp.: $-40^{\circ}\text{C}$ , 时间 time: $30\pm 3\text{ min}$ 2) 温度 Temp.: $+85^{\circ}\text{C}$ , 时间 time: $30\pm 3\text{ min}$ 5 cycles b. 测量条件 Measurement method: 试验后常温常湿环境中放置 ( $24\pm 2$ ) 小时后测量。 The component should be stabilized at normal condition for ( $24\pm 2$ ) hours before test.

## 8 焊接条件 Recommended Soldering Conditions

### 1、焊剂 Flux, Solder

① 使用松香助焊剂，禁止使用卤化物含量超过 0.2wt%的强酸性助焊剂。

Use rosin-based flux. Don't use highly acidic flux with halide content exceeding 0.2wt% (chlorine conversion value).

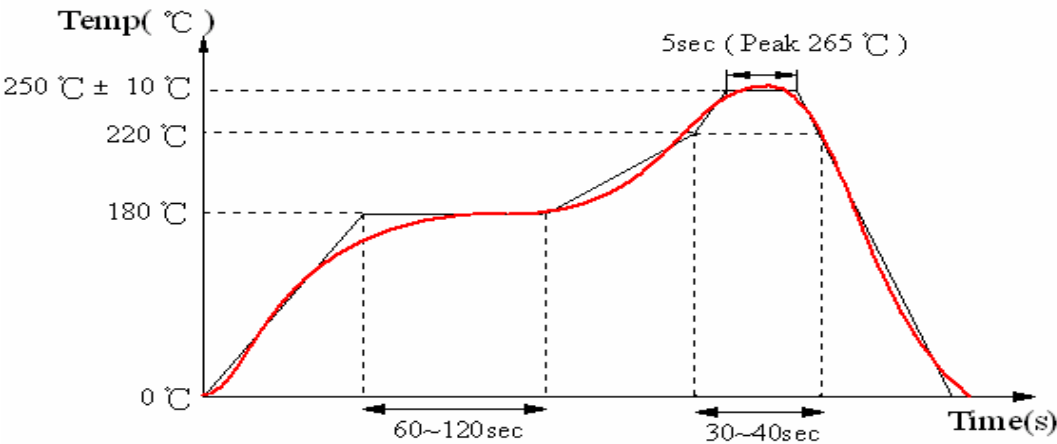
② 使用纯锡焊料 Use Sn solder.

### 2、回流焊条件 Reflow soldering conditions

●预热时，产品表温与焊料温度的温差最大不允许超出 150℃，焊接完后冷却时，产品表温与溶剂温度之间的温差最大不允许超出 100℃。预热不足有可能引发产品表面裂纹，导致产品品质下降。

Pre-heating should be in such a way that the temperature difference between solder and product surface is limited to 150℃ max. Cooling into solvent after soldering also should be in such a way that temperature difference is limited to 100℃ max. Unwrought pre-heating may cause cracks on the product, resulting in the deterioration of products quality.

●标准回流焊曲线 Standard soldering profile.



### 3、手工返工 Reworking with soldering iron

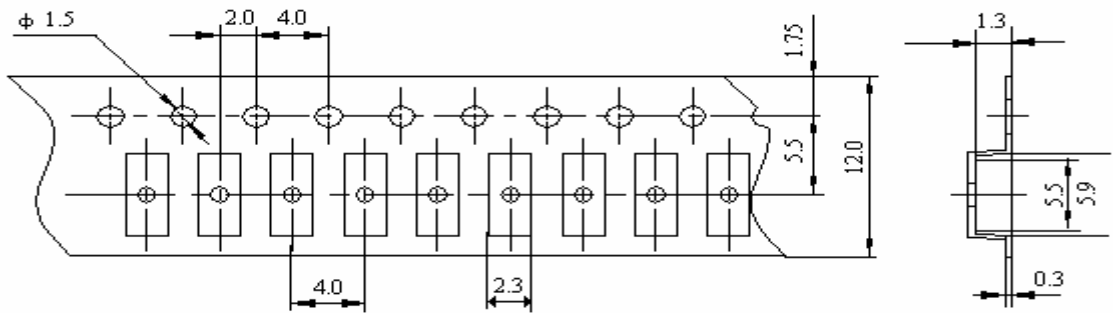
当使用电烙铁进行手工焊接时，以下条件必须严格遵守 The following conditions must be strictly followed when using a soldering iron.

预热 Pre-heating	150℃, 1 minute
尖端温度 Tip temperature	280℃ max
输出功率 Soldering iron output	30w max
电烙铁头尖端尺寸 End of soldering iron	φ3mm max
焊接时间 Soldering time	3 seconds max



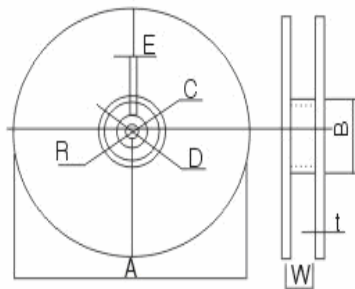
9 包装 Packaging

① 编带尺寸 Dimensions of Tape:



② 带轮尺寸 Dimensions of Reel

Unit: mm



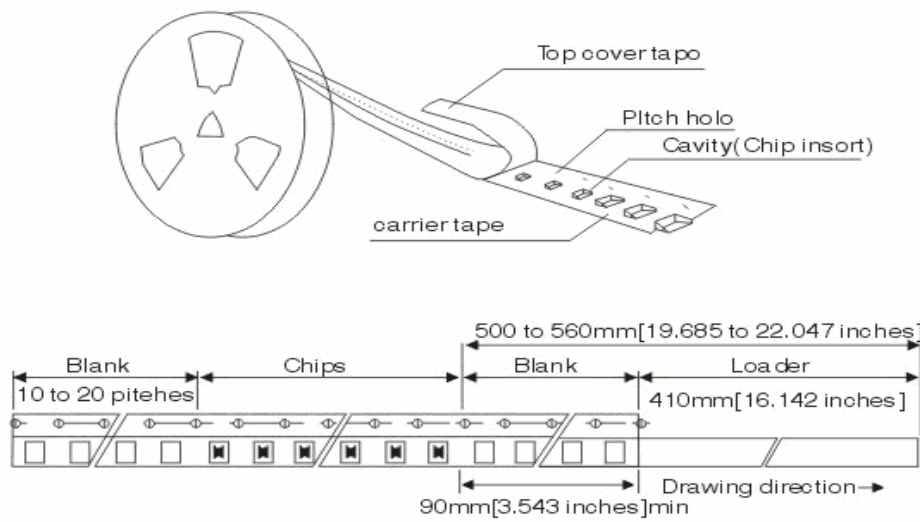
Reel material: PS (Polystyrene)

A	178 $\pm$ 2
B	60 $\pm$ 2
C	13.0 $\pm$ 0.5
D	21.0 $\pm$ 0.8
E	2.0 $\pm$ 0.5
W	12.5 $\pm$ 1.5
t	1.2 $\pm$ 0.2
R	1.0 $\pm$ 0.25

③ 编带抗拉强度 Pulling strength of tapes:

载带 Carrier tape	10N or more (1kgf or more)
上盖带 Cover tape	5N or more (1kgf or more)

④ 编带简图及拉伸方向 Taping figure and drawing direction:



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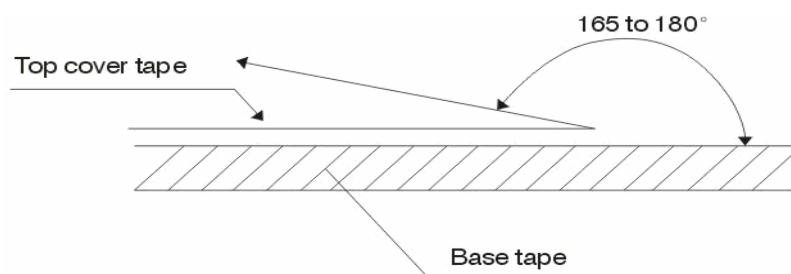
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⑤ 盖带的剥离强度 Peeling strength of cover tape:

盖带 Cover tape	0.3~0.7N (30gf~70gf)
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测试条件 Test condition:

- 1) 剥离角度 peel angle: 165°~180° vs. carrier tape.
- 2) 剥离速度 peel speed: 300mm/min±10%.

⑥ 包装数量 Packaging quantities: 3000 PCS / Reel

## 10 装箱清单及标志 Packing documents and marking

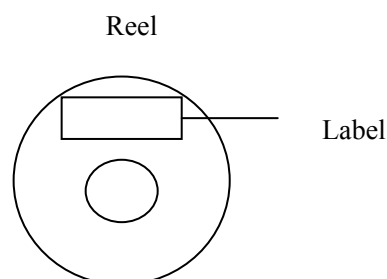
### 1. 包装文件 Packing documents

Packing includes the following:

- a. 装箱清单 Packing list.
- b. 合格证书 Certificate of compliance.

### 2. 盘上标记 Marking on reels:

- a 麦捷料号 MICROGATE Part No.
- b 生产批号 Lot number
- c 盘装数量 Quantity per reel
- d 检验员号 Inspector No.



以上内容必须在标签上注明.All above shall be shown on marking label

麦捷公司标签如下所示: MICROGATE marking label will be as following:

MICROGATE		
CUSTOMER:	P. O. NO	
CUSTOMER PART NO:	DATE CODE	LOT NO
MG PART NO:	QUANTITY	INSP. NO



MG PART NO

深圳市麦捷微电子科技股份有限公司

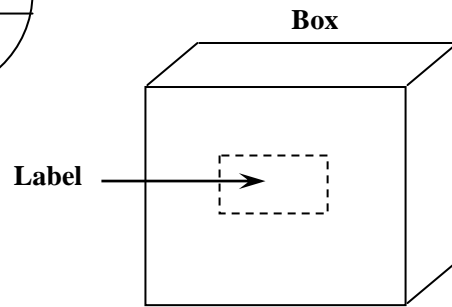
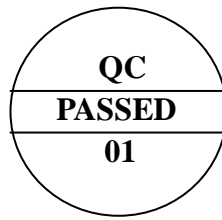
地址: 深圳市宝安区观澜镇高尔夫大道裕兴路

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传真(Fax): 0755-28085605

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检验合格后,检验员在标签上盖上合格章。合格章如下所示: The eligible reels will be pressed a mark onto the surface. The mark will be as following:



3. 内包装盒标记:Marking on inner box

- a. 型号 MICROGATE part No.
- b. 每盒数量 Quantity per box
- c. 包装日期 Date

以上内容必须在标签上注明(标签见 11.2 所示)。Above shall be shown on marking label (The marking label is shown in item 9.2).

4. 外包装箱标记 Marking on outer case:

1) 制造商 Manufacturer: “MICROGATE” ①

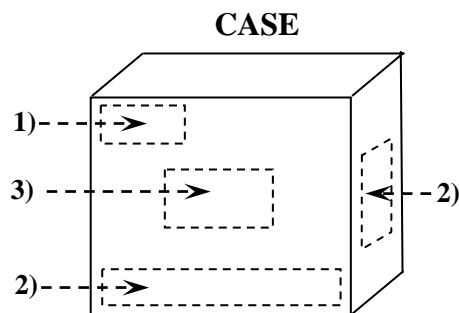
“中国深圳制造” “Made in Shenzhen CHINA”②

2) 发运标记 Ship marking:

“向上” “UP”, “小心轻放”“HAND CARE”, “防潮”“MOISTURE-PROOF”.

3) 包装标签包括以下内容 Packing label include the following:

- a. 型号 MICROGATE Part No
- b. 总数量 Total quantity per case
- c. 包装日期 Date;



以上内容必须在标签上注明。(参见 11.2 所示)

All above shall be shown on marking label.

(The marking label is shown in item 11.2)

## 11 保管 Storage

### ①. 保管期限 Storage period

距麦捷出厂检验时间六个月内，产品可以使用；检验时间可以通过包装外侧标记的检验号确认；若时间超出六个月，应检查焊接性能后方可使用。Products which inspected in MICROGATE over 6 months ago should be examined and used, which can be confirmed with inspection No. marked on the container. Solder ability should be checked if this period is exceeded.

### ②. 保存条件 Storage conditions

●存放货物的库房应满足以下条件 Products should be storage in the warehouse on the following conditions

温度 Temperature: -10 ~+ 40℃

湿度 Humidity : 30 to 70% relative humidity

不允许温、湿度有极剧变化。No rapid change on temperature and humidity

●禁止将产品保管在腐蚀性物质中，例如硫磺、氯气或者酸，否则将引起端头氧化，导致降低焊接性。Don't keep products in corrosive gases such as sulfur, chlorine gas or acid, or it may cause oxidization of electrode, resulting in poor solder ability.

●为了避免受潮气、灰尘等物质的影响，产品应保管于货架上。Products should be storage on the palette for the prevention of the influence from humidity, dust and so on.

●产品保管在库房中时，应避免热冲击，振动以及直接光照等等。Products should be storage in the warehouse without heat shock, vibration, and direct sunlight and so on.

●产品应密封包装 Products should be storage under the airtight packaged condition.

## APPENDIX A

## 納入仕様書改定履歴 MODIFY HISTORY OF SPECIFICATION

NO.	DATE	CONTENT	REV	APPROVED
1	2006-10-25	初稿 Constitute	1.0	张海恩